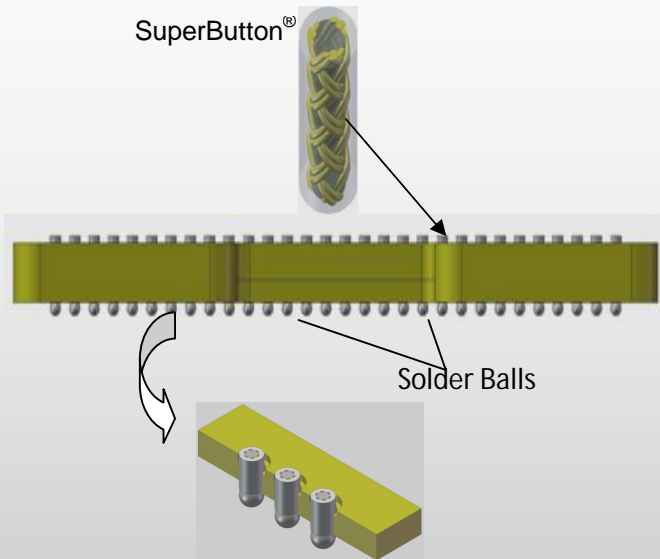


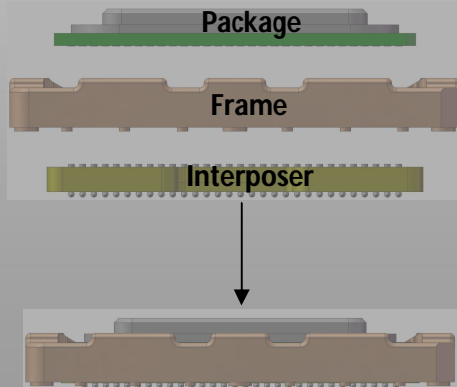
## A next generation technology

### Technology

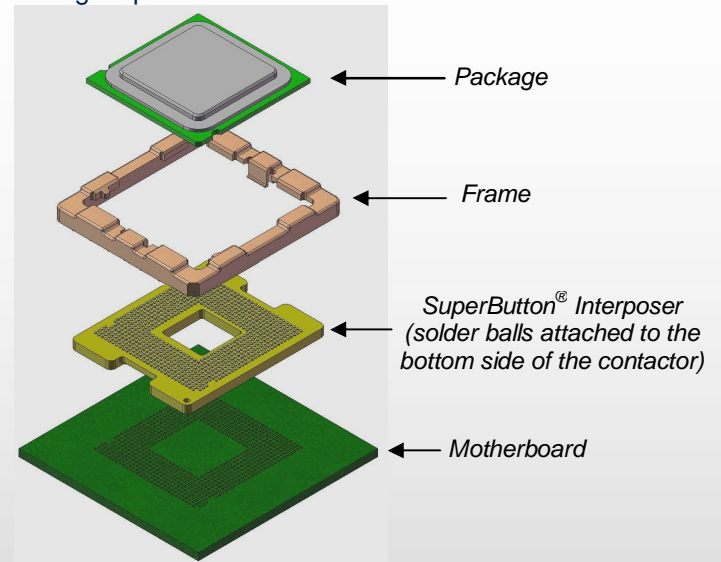
HCD's SuperButton® hybrid LGA technology is a revolutionary high performance and high density compression style interconnect provided in a standard solder able and RoHS compliant design. The solution includes a direct solder attach to the SuperButton® interposer as shown in the image below:



This design includes a SuperButton® interposer, which is an FR-4 carrier containing SuperButton® contact elements. Solder balls are attached to the bottom side of the SuperButton® contactor as shown above. A frame is placed around the SuperButton® interposer to align the package with the SuperButton® contacts as highlighted in the image below. The total assembly height can be adjusted as necessary to accommodate system design.



By designing it to be solder able, the hybrid interposer can be used on a standard circuit board without the need for a hard gold pad interface.



### Common Applications

- Package-to-Board
- Board-to-Board
- Board-to-Flex

Features	Benefits
Low Profile	Shorter signal path results in high frequency, low Cres and low self inductance
High Density, Low Pitch	Saves space on PCB
No gold required on the PCB pads	Saves cost
Reliability	<ul style="list-style-type: none"> <li>• Up to 12 redundant contact points per button</li> <li>• Extremely stable connection over time and temperature</li> </ul>